

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-22 (canceled).

Claim 23 (currently amended): A ceramic multilayer substrate comprising:
a ceramic laminate including a plurality of ceramic layers, having a first main surface, and including internal circuit elements disposed inside of the laminate;
a resin layer having a bonding surface in contact with the first main surface of the ceramic laminate and a mounting surface opposite to the bonding surface;
external electrodes, each disposed on the mounting surface of the resin layer and electrically connected to at least one of the internal circuit elements of the ceramic laminate; and
a ground electrode disposed inside of the resin layer; wherein the ground electrode is arranged to overlap at least one of the external electrodes in a direction of lamination of the plurality of ceramic layers.

Claim 24 (previously presented): The ceramic multilayer substrate according to Claim 23, wherein the ground electrode includes a sintered metal integrally baked with the ceramic laminate.

Claim 25 (previously presented): The ceramic multilayer substrate according to Claim 23, further comprising a first circuit component mounted on the first main surface and covered with the resin layer, wherein the ground electrode are disposed on a side that is closer to the mounting surface than the first circuit component.

Claim 26 (previously presented): The ceramic multilayer substrate according to Claim 25, wherein the first circuit component is disposed within a region defined by projecting the ground electrode on the first main surface.

Claim 27 (previously presented): The ceramic multilayer substrate according to Claim 23, further comprising relay electrodes disposed so as to extend along the first main surface, wherein electrical connections from the external electrodes to the internal circuit elements are provided through the relay electrodes.

Claim 28 (previously presented): The ceramic multilayer substrate according to Claim 23, wherein the ceramic laminate comprises a second main surface on an opposite side to the first main surface, and a second circuit component is mounted on the second main surface.

Claim 29 (previously presented): The ceramic multilayer substrate according to Claim 28, wherein a conductive case is disposed on the second main surface to cover the second circuit component.

Claim 30 (withdrawn): The ceramic multilayer substrate according to Claim 28, wherein the second circuit component on the second main surface is covered with a molded resin layer.

Claim 31-35 (canceled).